



# Semiconductor Photon Detectors

## Part2

Gerhard Lutz

*PNSensor GmbH, München*

*for the*

*MPI Semiconductor Laboratory, Otto Hahn Ring 6, D 81739 München*

**3rd Joint ILIAS-CERN-DESY Axion-WIMPs training-workshop**

Patras, Greece  
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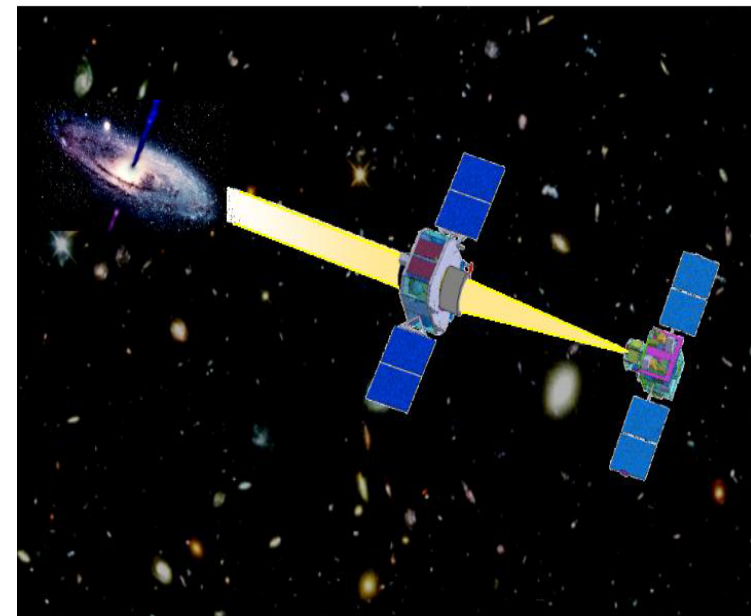
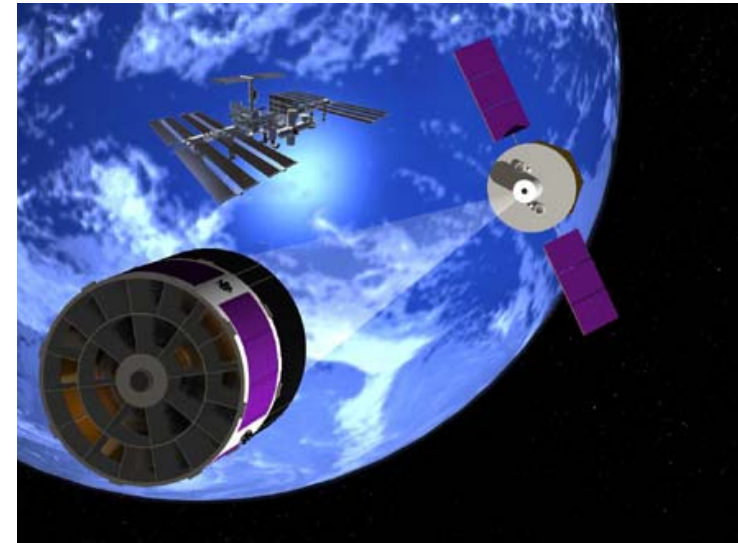
# DEPFETs



# DEPFET Detectors in Institute Projects

## X-ray Astronomy

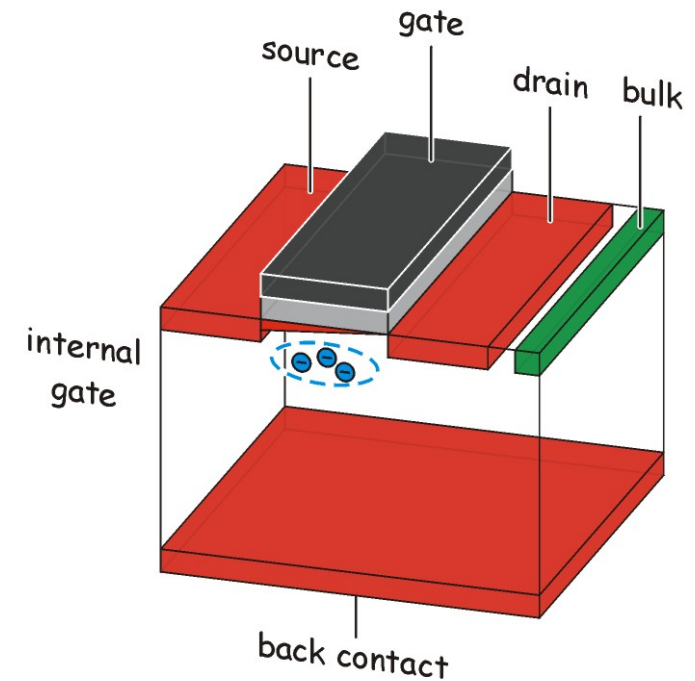
- **XEUS (X-ray Evolving Universe Spectroscopy)**
  - **Scientific aim:**
  - **investigation of the universe at an early evolution stage:**
    - early black holes
    - evolution and clustering of galaxies
    - evolution of element synthesis
  - **Observation of distant faint objects:**
    - Large collection area
    - Large focal length (50m)
    - Separate satellites
- **SIMBOL-X**
  - **First science objective :**
  - **astrophysics around black holes**
    - X-ray binaries Active Galactic Nuclei (supermassive active BHs)
    - The Galactic Centre (supermassive quiescent BHs)
  - **Hard X-ray sensitivity (0.5 to 80 keV)**
    - Large focal length (30m)
    - Separate satellites





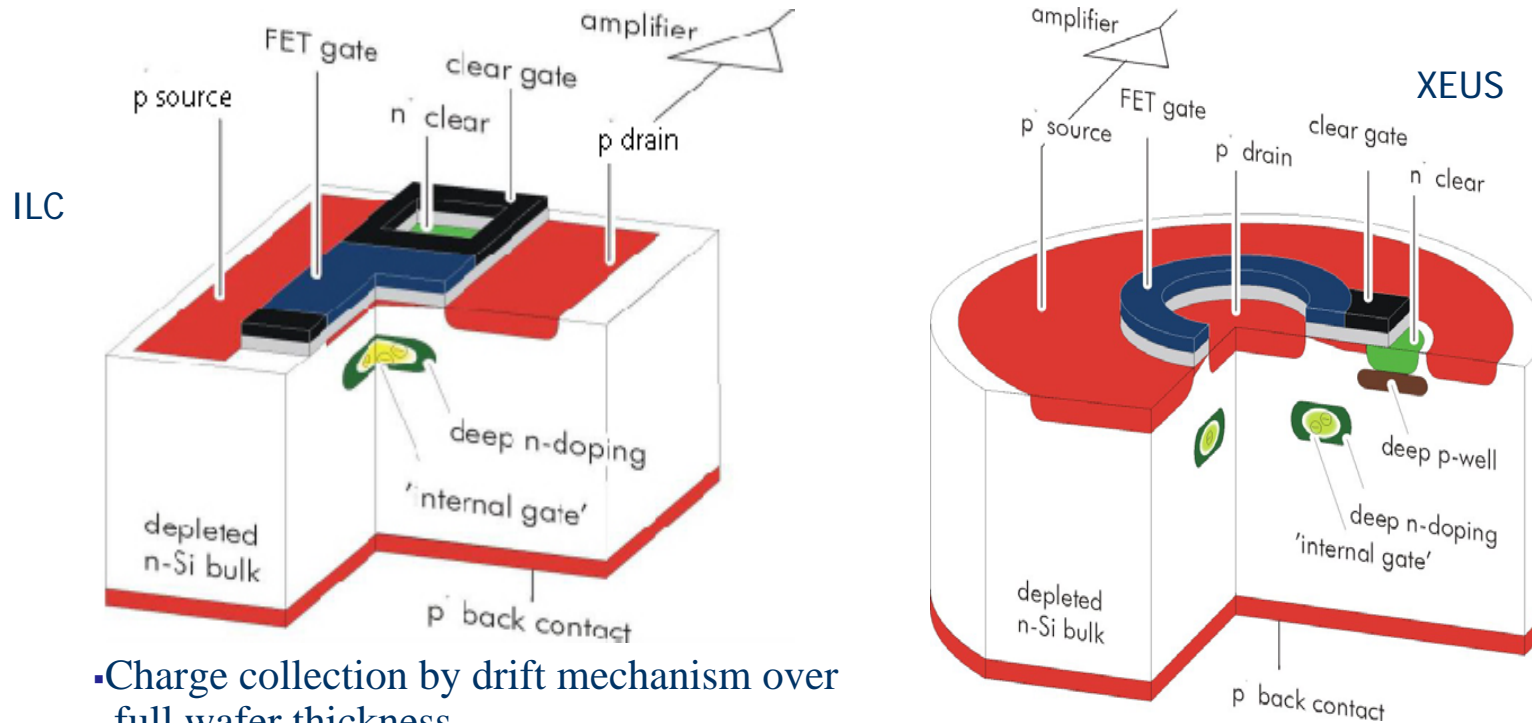
# DEPFET Function principle

- Field effect transistor on top of fully depleted bulk
- All charge generated in fully depleted bulk drifts into potential minimum underneath the transistor channel steers the transistor current
- Clearing by positive pulse on clear electrode
- **Combined function of sensor and amplifier**





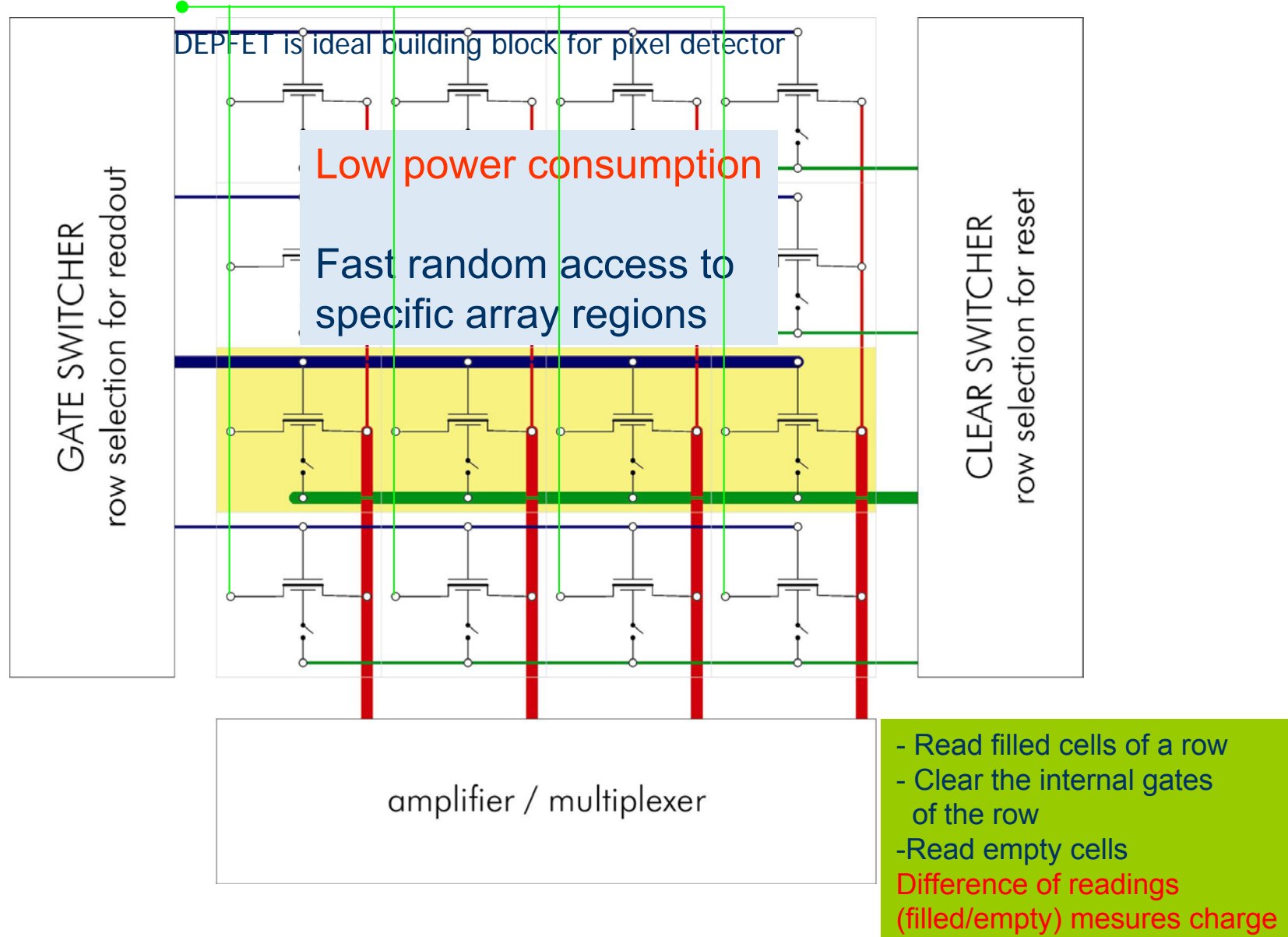
# DEPFET properties



- Charge collection by drift mechanism over full wafer thickness
- low capacitance ► low noise
- Signal charge remains undisturbed by readout ► repeated readout
- Complete clearing of signal charge ► no reset noise
- Full sensitivity over whole bulk ► large signal for m.i.p.; X-ray sens.
- Thin radiation entrance window on backside ► X-ray sensitivity
- Charge collection also in turned off mode ► low power consumption
- Measurement at place of generation ► no charge transfer (loss) ►  
Operation over very large temperature range ► no cooling needed



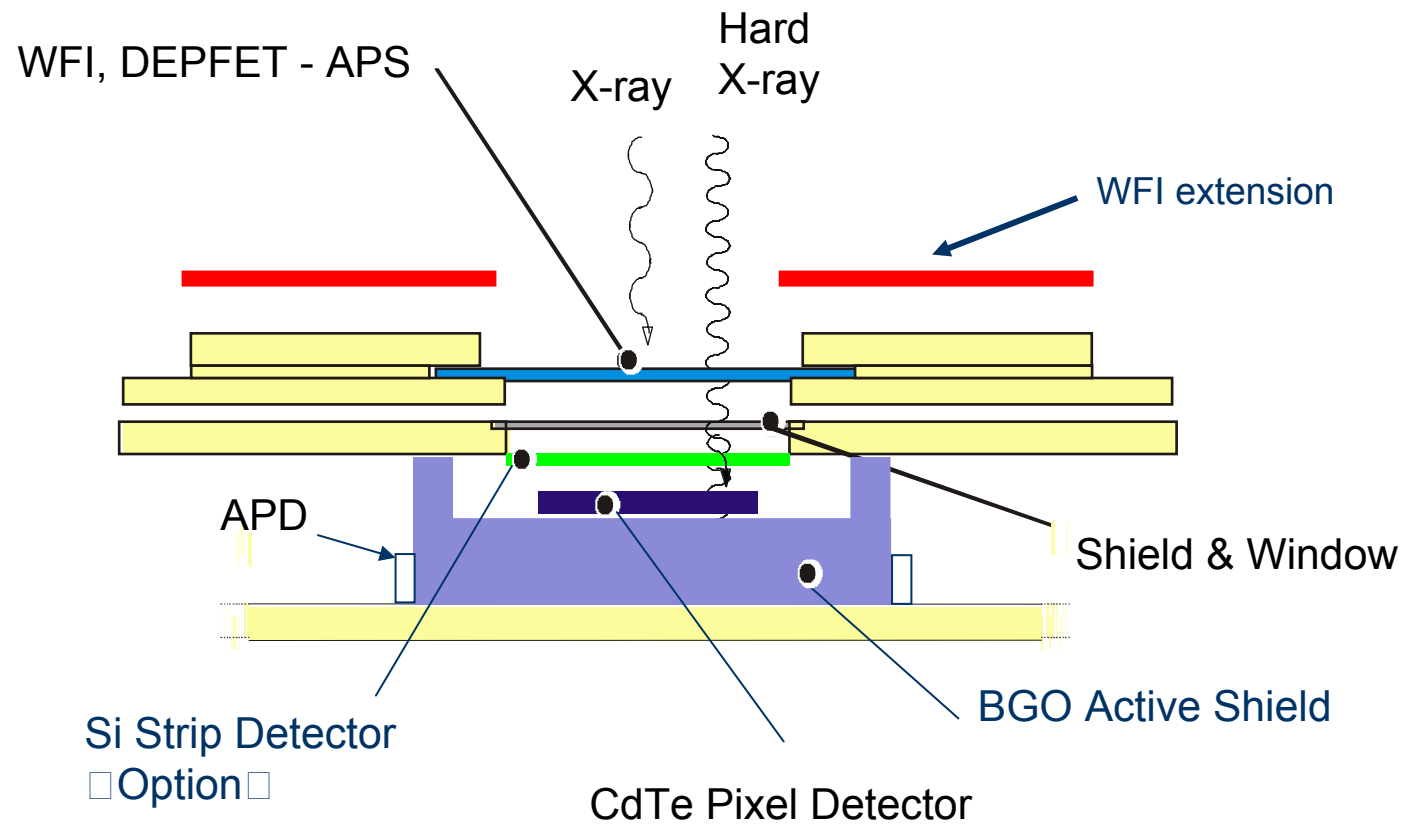
# DEPFET pixel matrix





# DEPFETs for XEUS

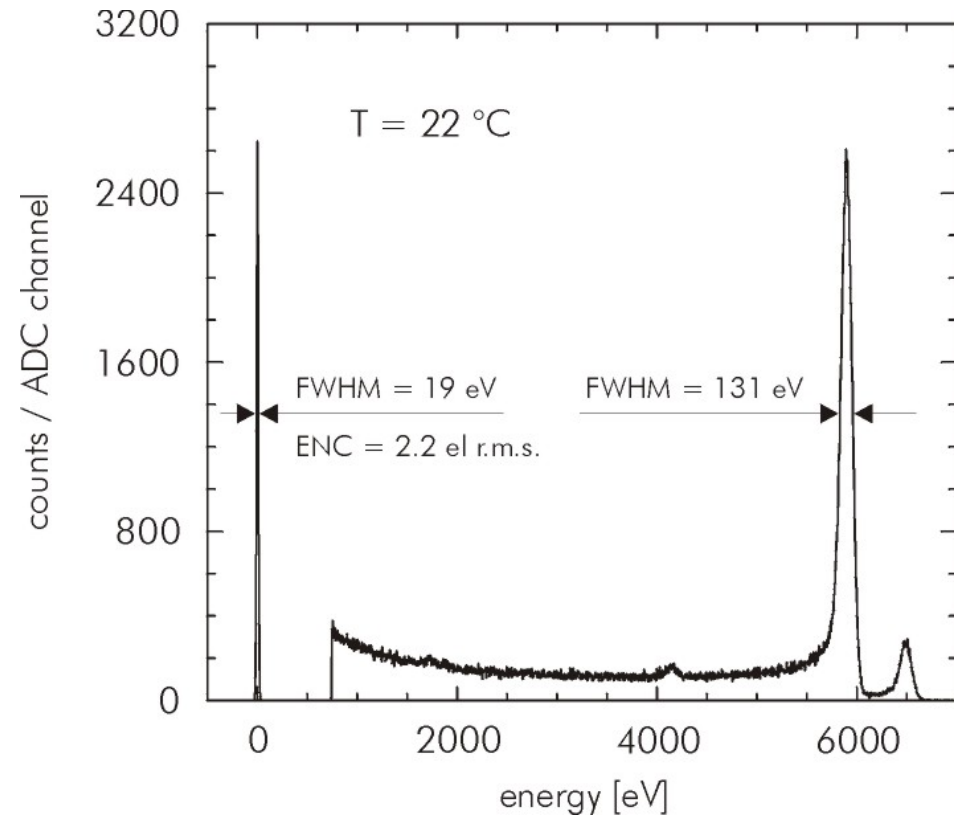
- Focal imaging: Wide Field Imager
  - pixel size  $75 \times 75 \mu\text{m}^2$
  - 1024x1024 pixels
  - $7.7 \times 7.7 \text{ cm}^2$





# XEUS DEPFET single pixel performance

- Source follower readout
- **Pulsed clear** operation with **6 $\mu$ s** time continuous filter
- **Room temperature** (22° C)
  
- **Noise peak:**  $\sigma = 2.2$  e- ENC
  
- **Energy resolution at 5.9keV:**  
FWHM @ 5.9 keV = 131 eV

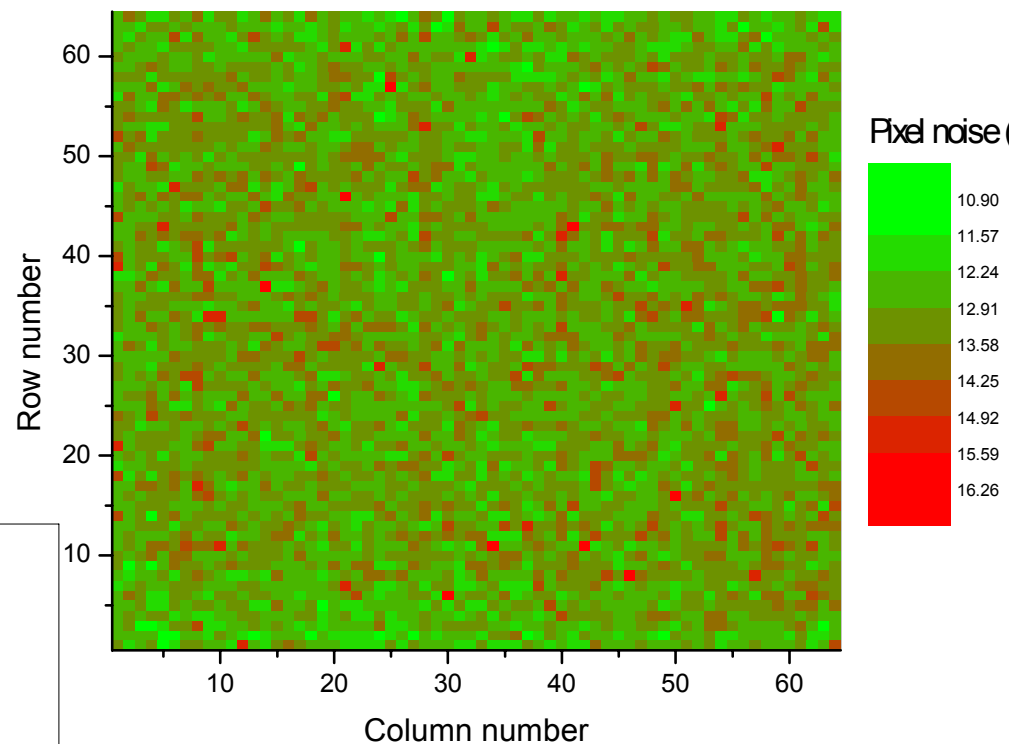
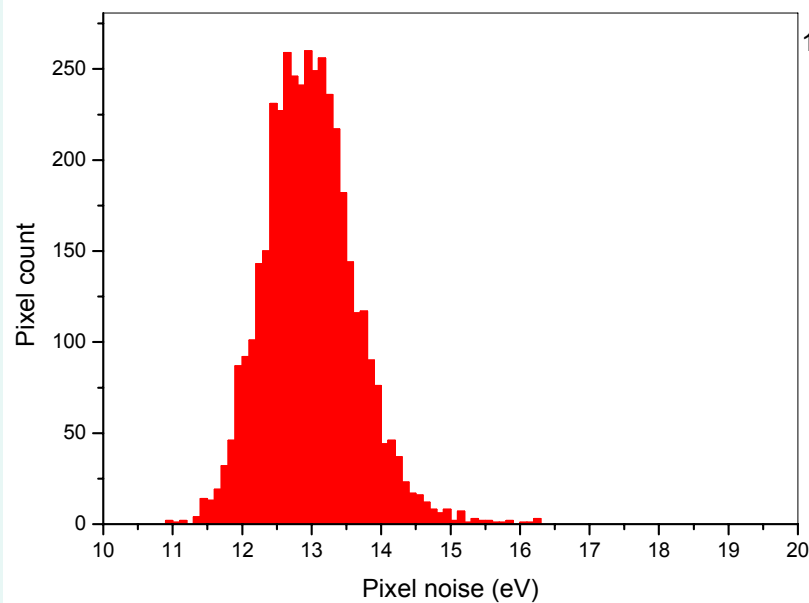






# XEUS DEPFET matrix performance: noise

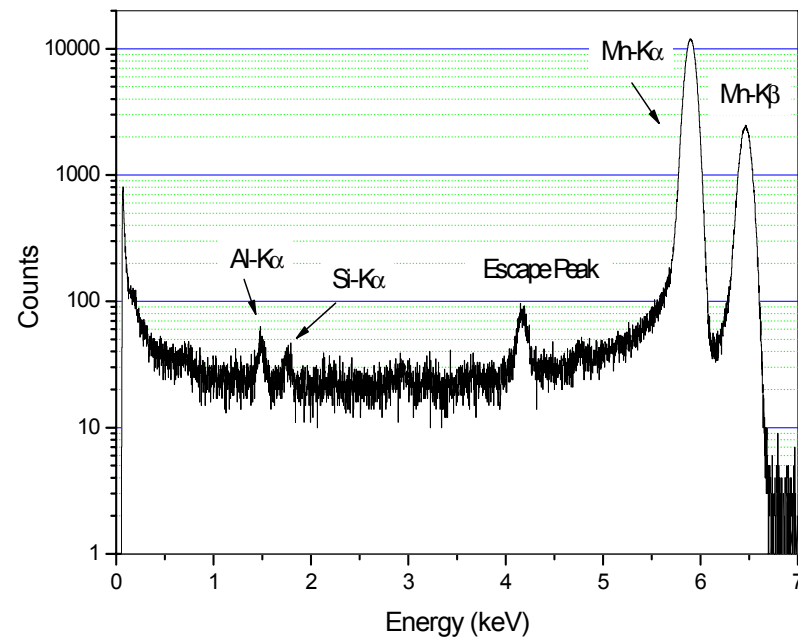
- Test of 64x64 pixel detector
- Noise performance at -40 C
- Average noise 3.8 electrons
- Noise dispersion ca. 10%





# XEUS DEPFET matrix performance: spectrum

- Test of 64x64 pixel detector
- $^{55}\text{Fe}$  spectrum at -50 C
- Pixel current 30  $\mu\text{A}$
- Line processing time 25  $\mu\text{s}$
  
- **Energy resolution:**
- **126 eV FWHM @ Mn-K $\alpha$  Line**
- **corresponding to 4.9 e- ENC**



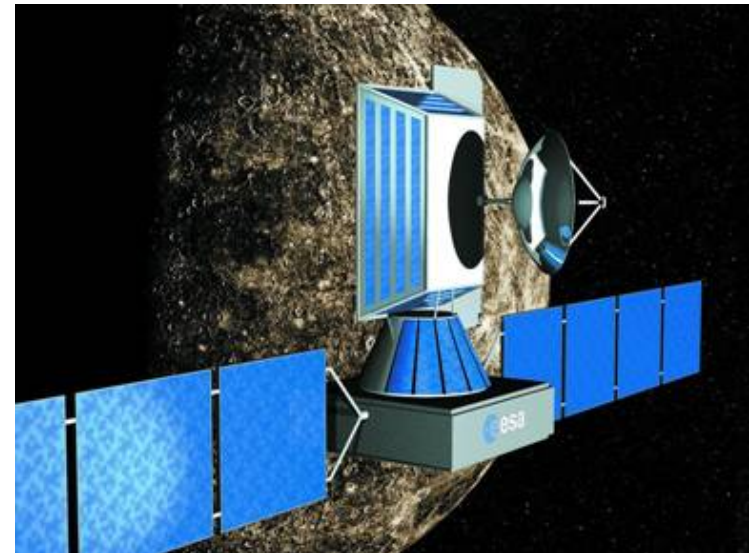
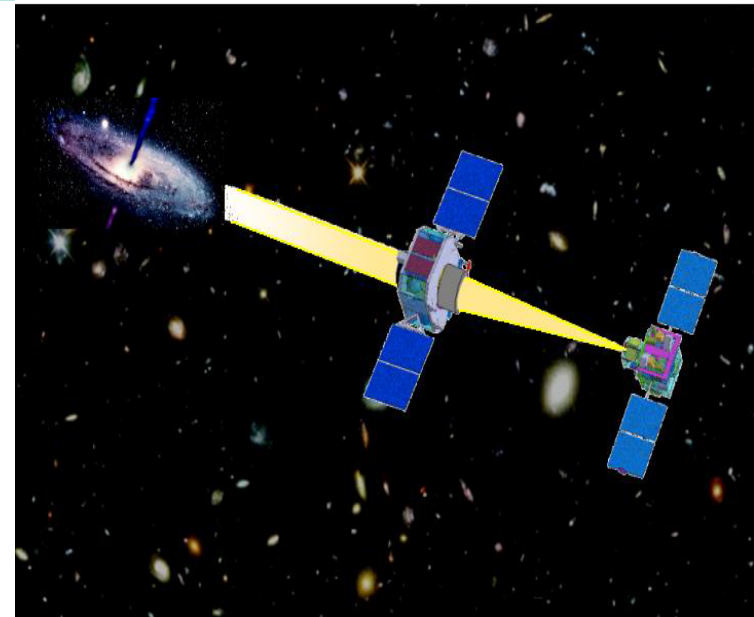


# Macro Pixel Detectors



# Macropixel DEPFET detectors

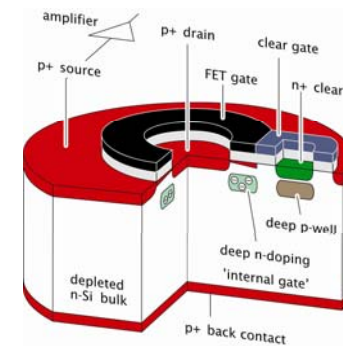
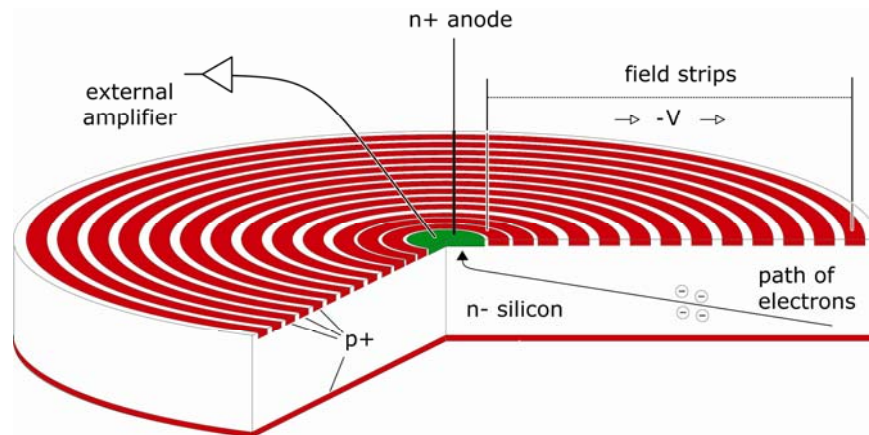
- Pixel detectors with large cell size needed in order to match pixel size to optical property of telescope
- Examples:
  - **SIMBOL X**
    - **astrophysics around black holes**  
X-ray binaries, Active Galactic Nuclei  
The Galactic Centre
    - **Hard X-ray sensitivity (0.5 to 80 keV)**  
Large focal length (30m)  
Separate satellites
  - **BEPI Colombo**  
Mercury planetary orbiter
    - X-ray spectrometer



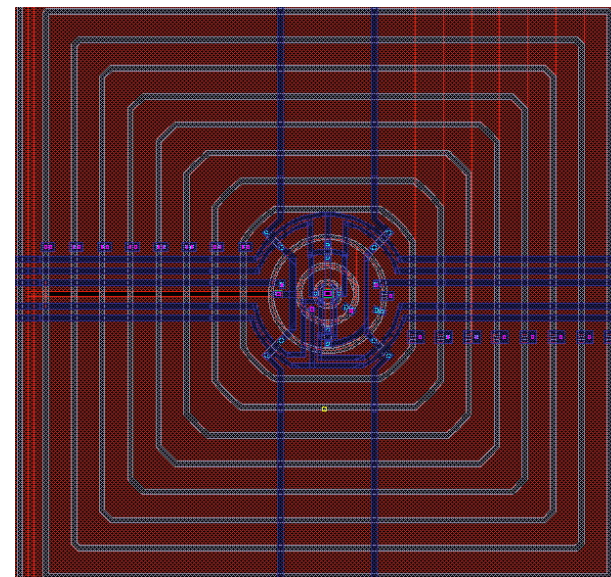


# Macropixel DEPFET detectors

- Combination of SDD (Silicon Drift Diode) with DEPFET



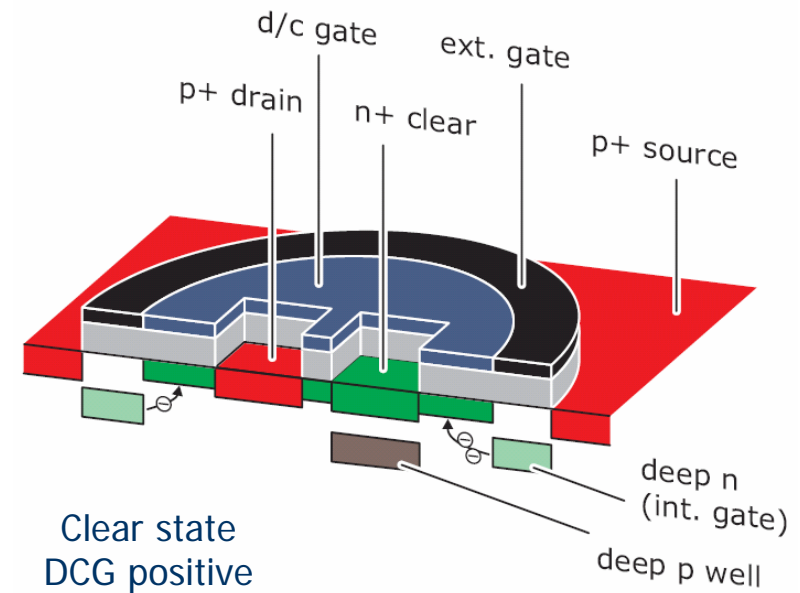
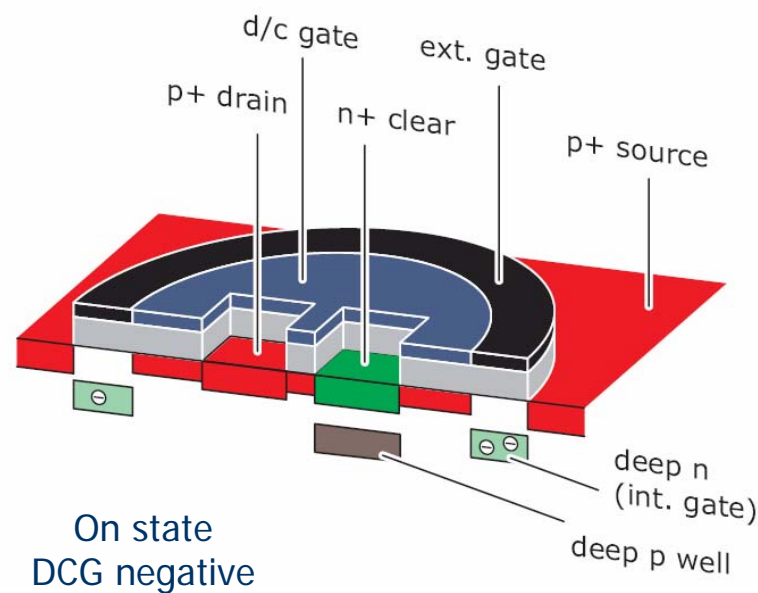
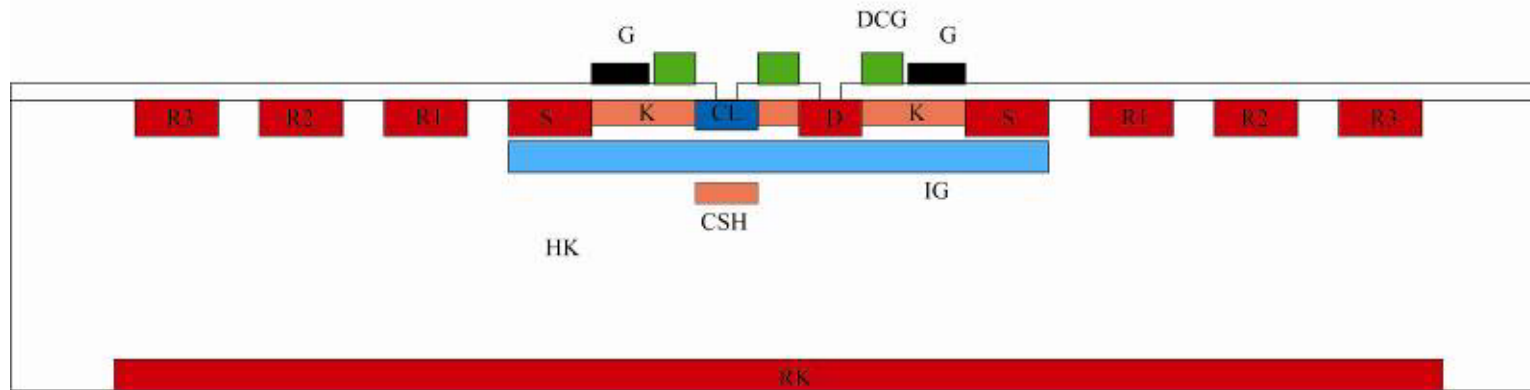
- Each cell consist of drift diode with DEPFET as readout element
- Cell size can be chosen (adapted to the application) over a very wide range





# DCG type DEPFET

- New type of DEPFET allows operation with lower clear voltages

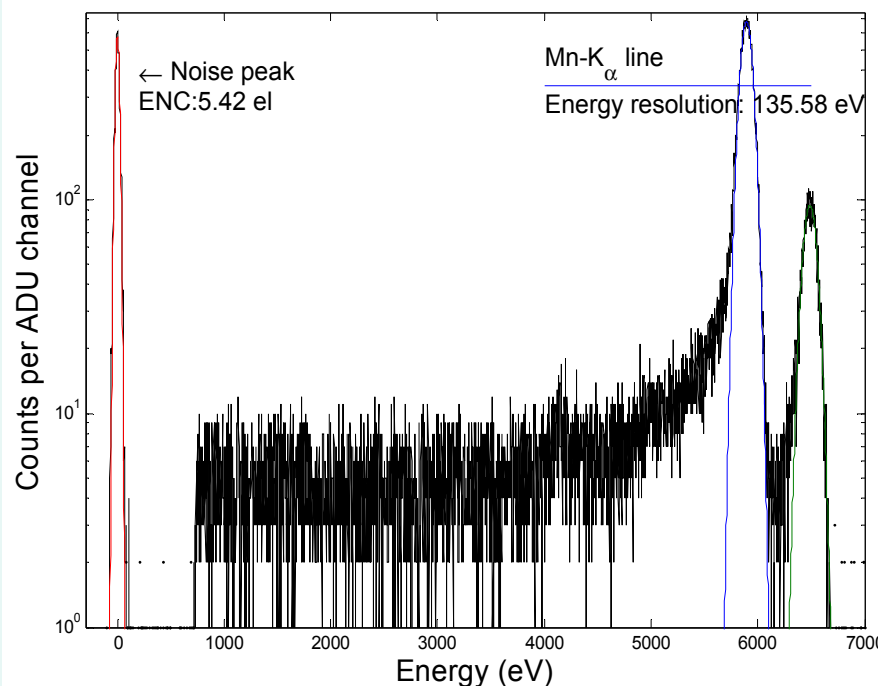




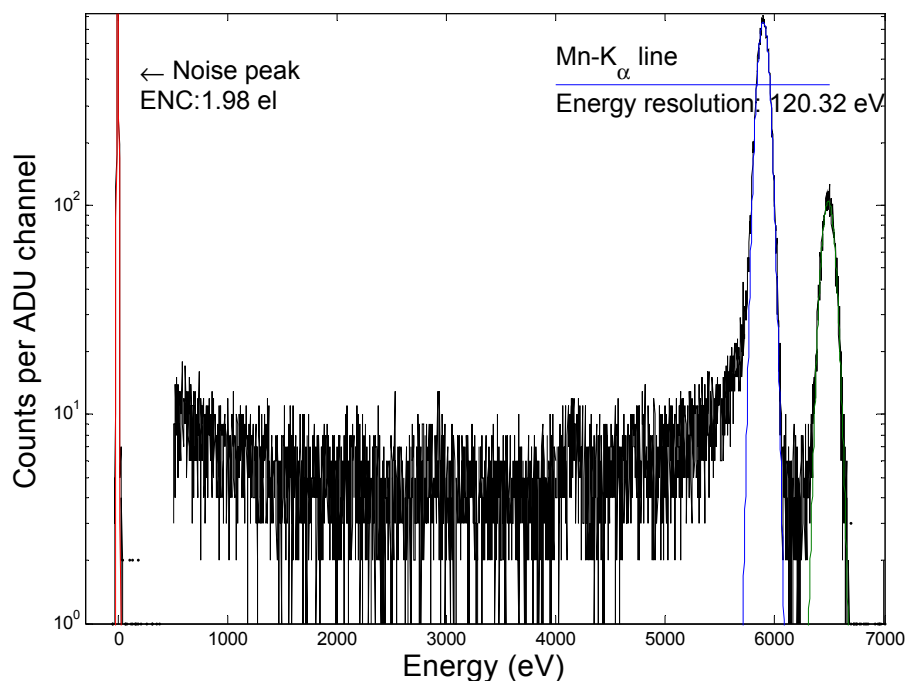
## Macropixel DEPFET detectors: results

- Devices produced: Single pixels and 4x4 matrices of 1x1mm<sup>2</sup> pixel size with normal and DCG DEPFETS
- In production: 64x64 matrices with 0.5x0.5 mm<sup>2</sup> pixel size

Single cell measurements at different conditions for the two device types



DCG type: T= -20 C, shaping 6 $\mu$ s, I=100 $\mu$ A  
Noise ENC=5.4 electrons



„normal“ type: T= -30 C, shaping 6 $\mu$ s, I=40 $\mu$ A  
Noise ENC=2 electrons

Difference in performance is due to the large chosen geometry in the DCG type



# Single (optical) photon detection





# Single (optical) photon detection

- Photon Detectors described so far can be used for:
  - Single X-ray photon detection producing many electrons/photon
  - Measure energy, position and time of arrival
  - For optical photons only flux measurements are possible
- New applications in
  - High Time Resolution Astronomy (HTRA) and
  - Astroparticle Physics

require

- detection of single optical photons with
  - high quantum efficiency



# Detector requirements

- **High time resolution astronomy:**
  - Observation of faint (distant) periodically varying objects producing sometimes less than one (optical) photon per period:
    - Rotating neutron stars
    - Close binary objects (e.g. rotating around black holes)
  - Time resolution (frame rate) better than 1 millisecond
    - less than 1 electron on average per frame
    - Sensitivity for single electron
- **Astro-Particle Physics:**
  - Observation of high energy showers in atmosphere:
    - Optical photons from scintillation and Cerenkov light
    - Night sky background
  - High time resolution (ns) for
    - Suppression of Night sky background
    - Measurement of shower angle



# Single Optical Photon Detection

- **Conversion properties:**
  - Only one electron produced in conversion process (photoelectric effect)
  - Short penetration length for blue light in silicon
- **Single optical photon detection** requires either
  - Improvement of charge measuring precision to a small fraction of the elementary charge  
**possible with DEPFET ping-pong RNDR structures** but requires very large readout time
  - or**
  - An intrinsic charge multiplication process (avalanche multiplication)  
**used since considerable time** but has problems with quantum efficiency due to obstruction of the entrance window

**Both methods are being developed at MPI**



# RNDR (Ping-Pong) Readout



# RNDR (Repeated Non Destructive Read) DEPFETs

- Measure charge by difference of DEPFET current with/without charge in internal gate
- Do not destroy charge when removing from internal gate but
- Move charge to intermediate storage place so as to be able to move it back to internal gate for renewed measurement
- Charge may also be moved repeatedly between internal gates of two neighboring DEPFETs
- Serial noise drops with square root of number of measurements
- This **holds also for serial 1/f noise**
- Closed (circular) and Open (linear) double DEPFET structures produced
- Results of linear structures to be presented

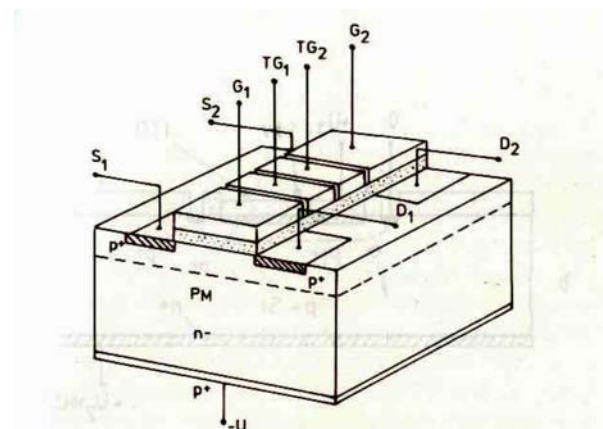
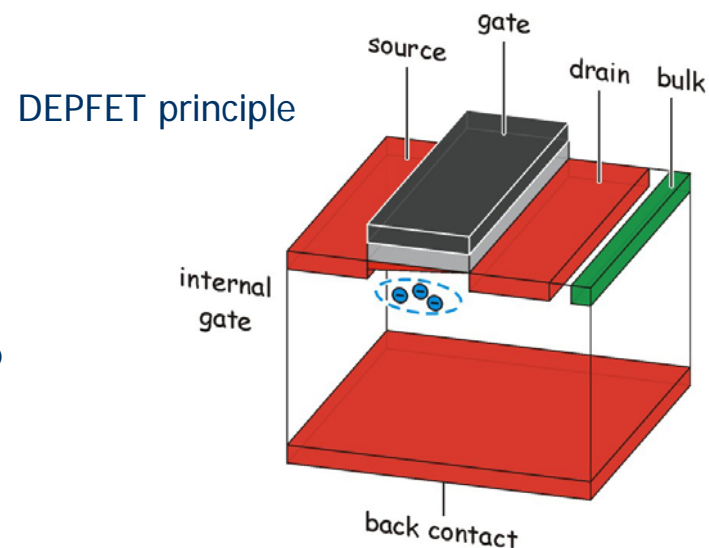


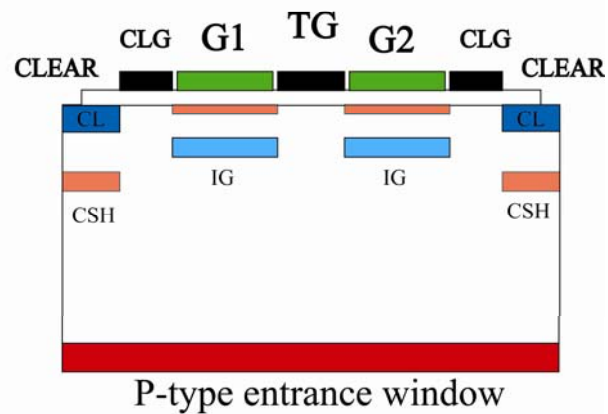
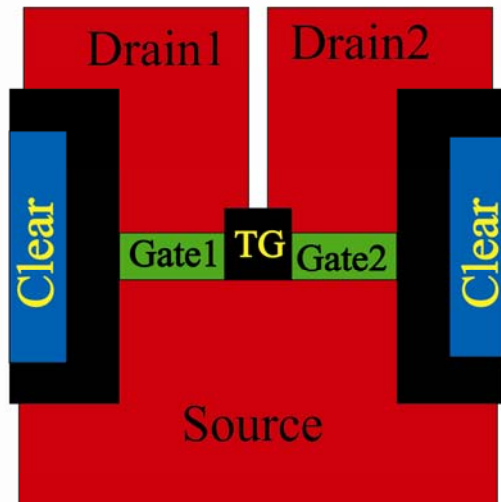
Fig. 29. Double gate DEPMOS transistor with transfer gates TG<sub>1</sub> and TG<sub>2</sub>. Charge can be shifted from gate G<sub>1</sub> to gate G<sub>2</sub> for differential measurements.

*J.Kemmer and G.Lutz: New Detector Concepts, NIM A253 (1987) 365-377*

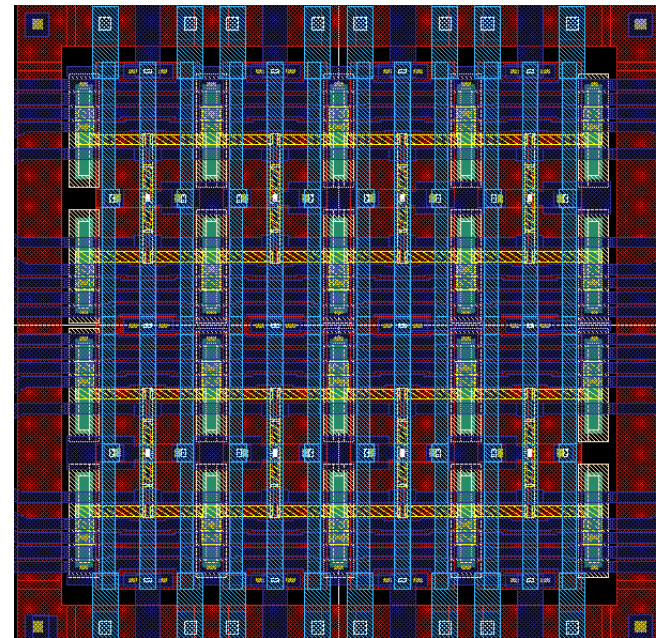


# RNDR linear structure

- Function principle



Layout of 4x4 matrix : 75  $\mu\text{m}$  pixels

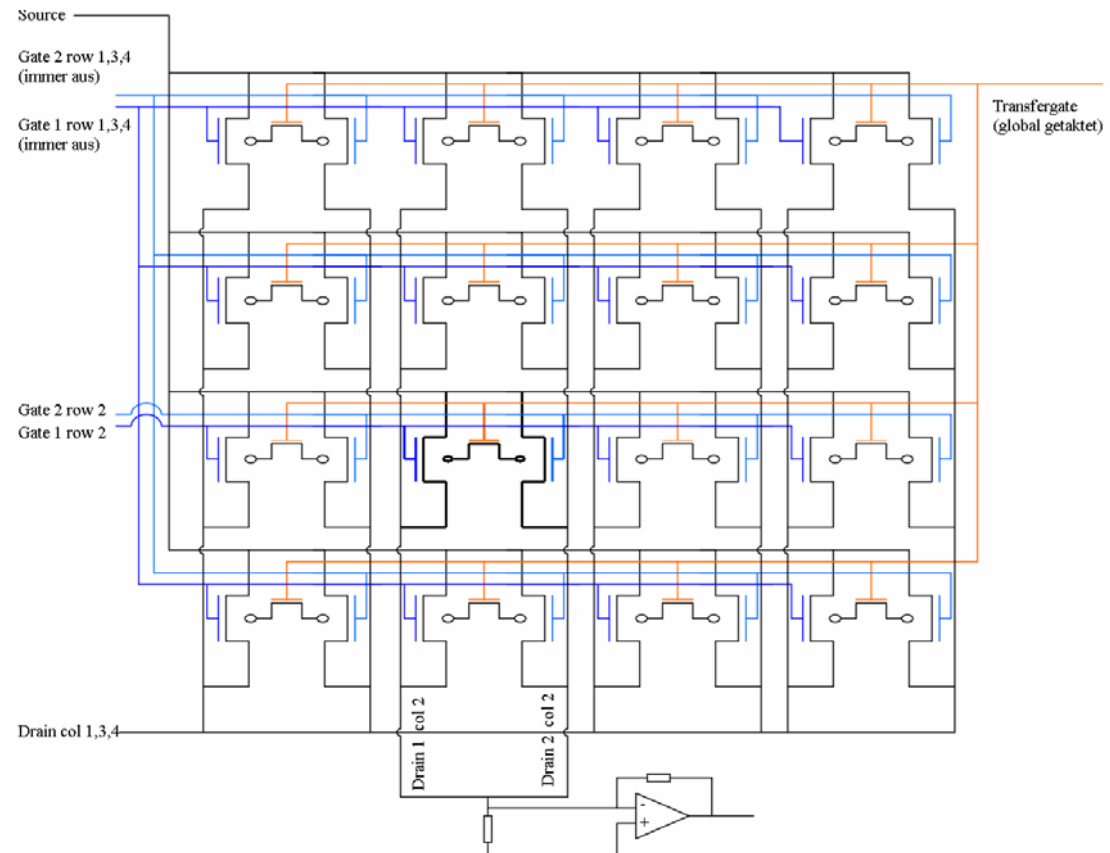




# RNDR tests: measuring setup

Authors: S. Wöfl, G. Lutz, L. Strüder, P. Lechner, R.H. Richter, J. Treis, S. Herrmann, M. Porro

- Test of one pixel in a 4x4 matrix
- Turn on one DEPFET at a time (with the help of the corresponding gate)
- Measure current with full and empty gate (before and after transfer of charge to neighbor)
- Calculate current difference (as measure of the signal charge)
- Repeat procedure for neighbour DEPFET
- Repeat complete cycle many times
- Average the current differences of all measurements

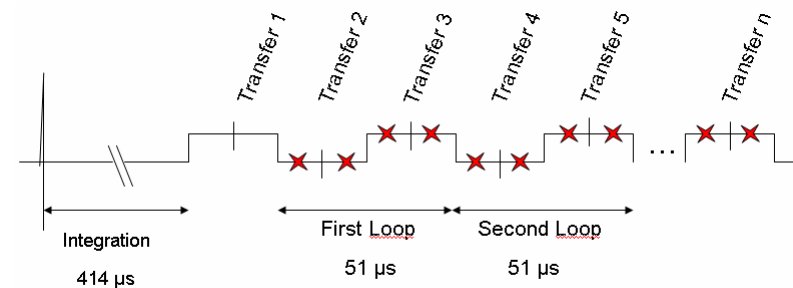




# RNDR tests: operating conditions

Authors: *S. Wölfl, G. Lutz, L. Strüder, P. Lechner, R.H. Richter, J. Treis, S. Herrmann, M. Porro*

- Operating Temperature -45 C
- Leakage current: 1 electron in 14 ms
- Single sampling averages current over 10  $\mu\text{s}$
- 1 loop = 4 single samplings takes 51  $\mu\text{s}$
- Injection of laser pulse during integration time of 414  $\mu\text{s}$



DEPFET on	2	2	1	1	2	2	1	1	2	2		2	2	1
Charge in DEPFET	1/2	1	1	2	2	1	1	2	2	1		2	1	1

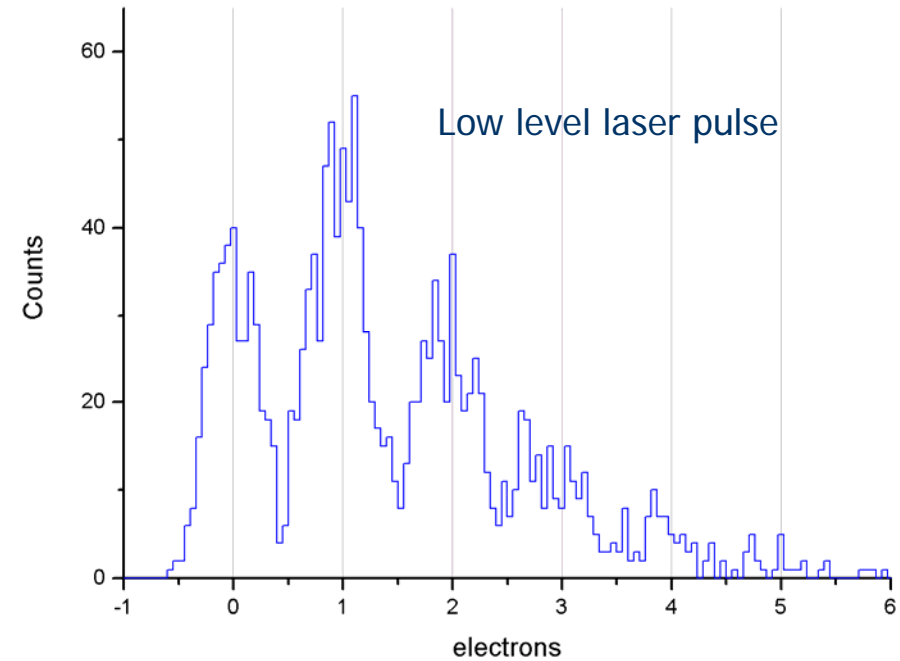
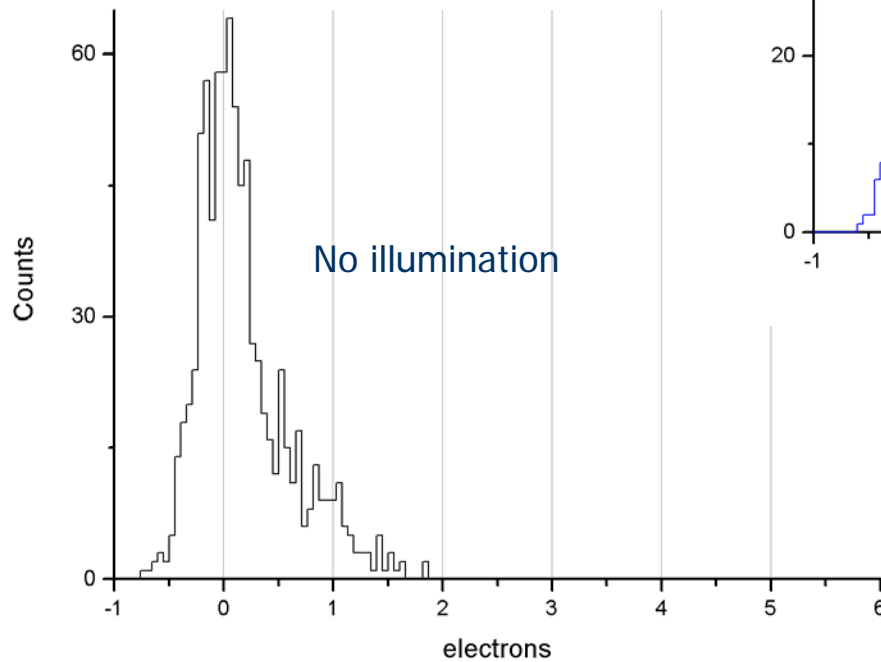
Depfet 1   
 Depfet 2   
 Sampling time x





# RNDR tests: noise and very low level laser light

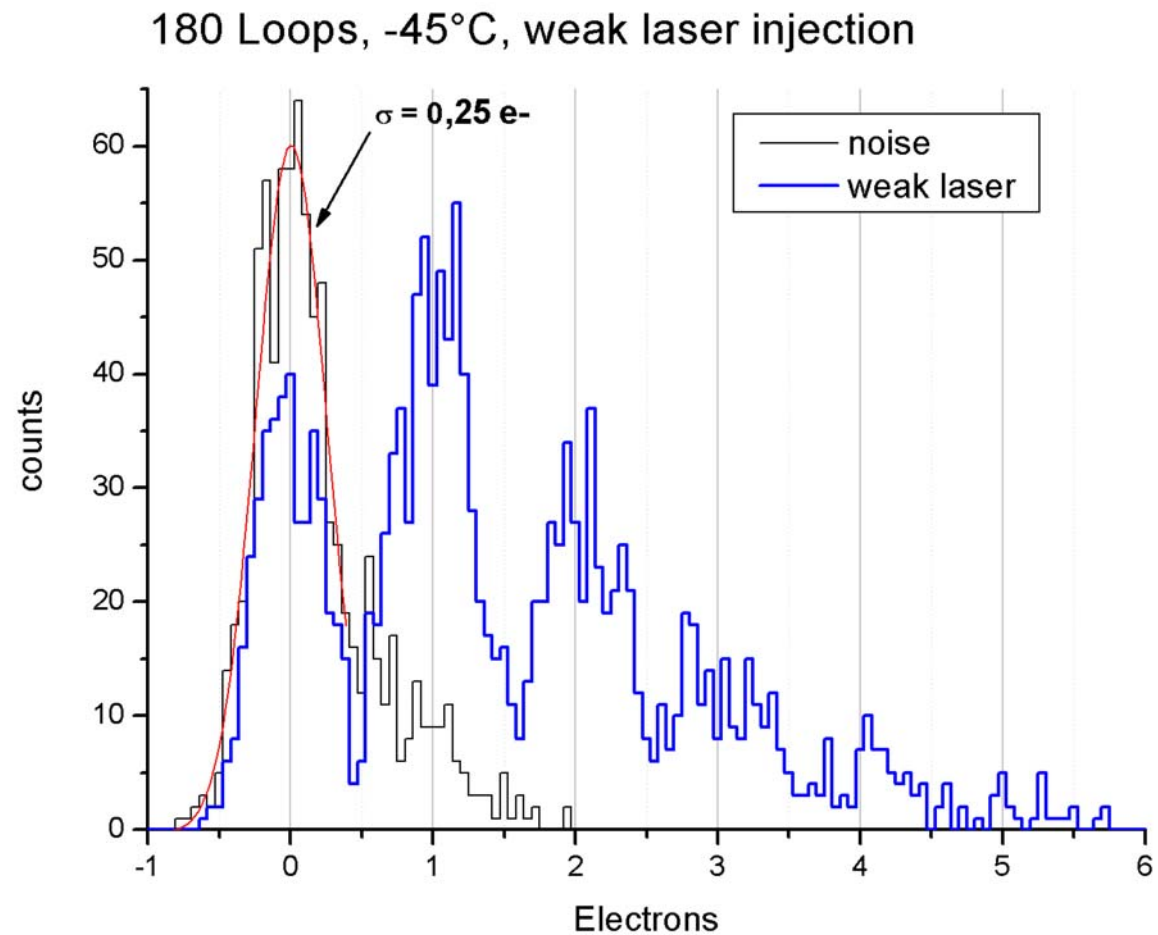
- Measurement of charge with 180 loops corresponding to 9.2 ms total measuring time
- Charge calibration with  $^{55}\text{Fe}$  source





# RNDR tests: noise and very low level laser light

- Fit to noise peak: 0,25 electrons rms
- Distinct peaks for 0, 1, 2, ... electrons

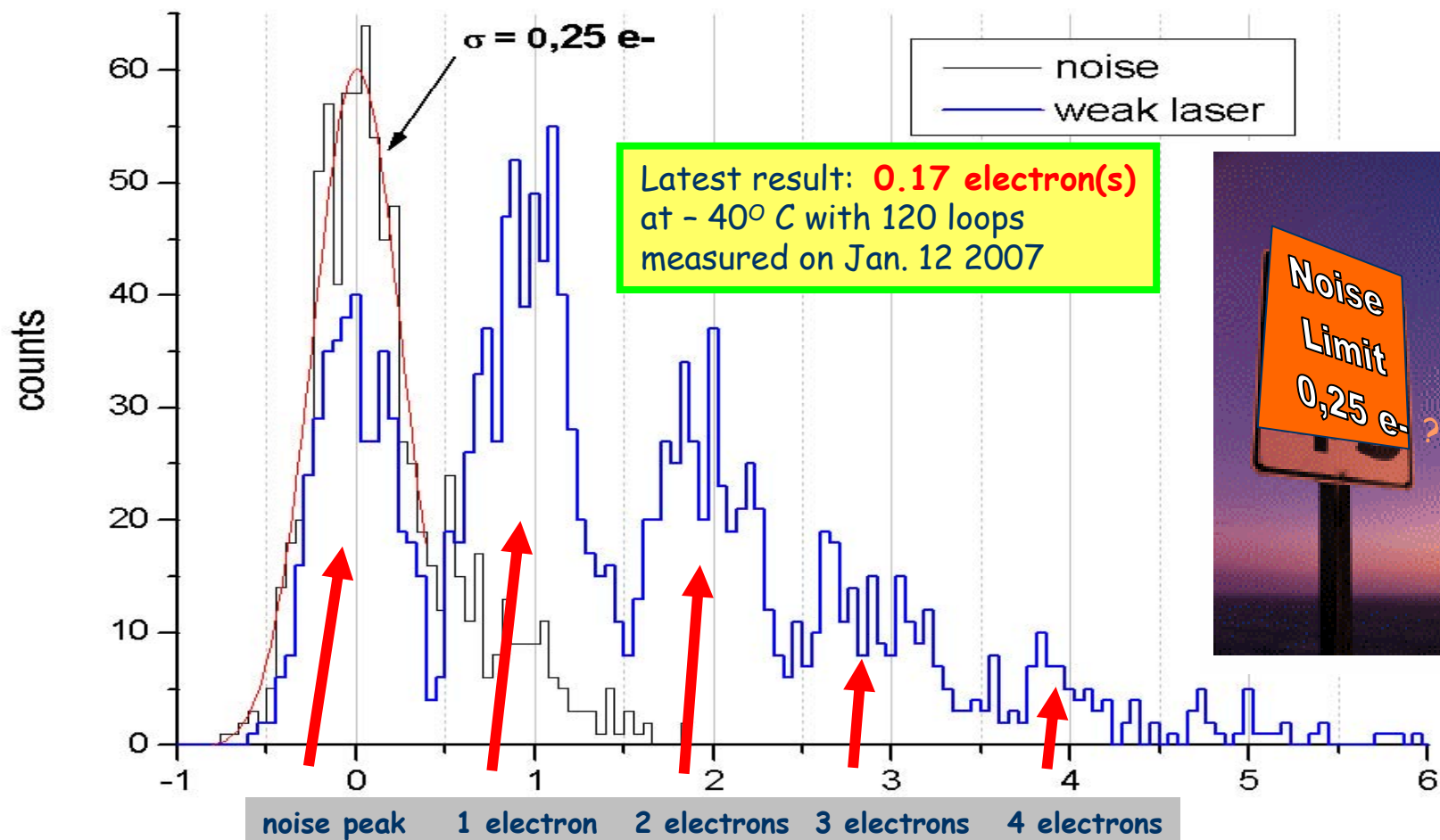




# Poisson distributed photons

- Fit to noise peak: 0,25 electrons rms
- Distinct peaks for 0, 1, 2, ... electrons

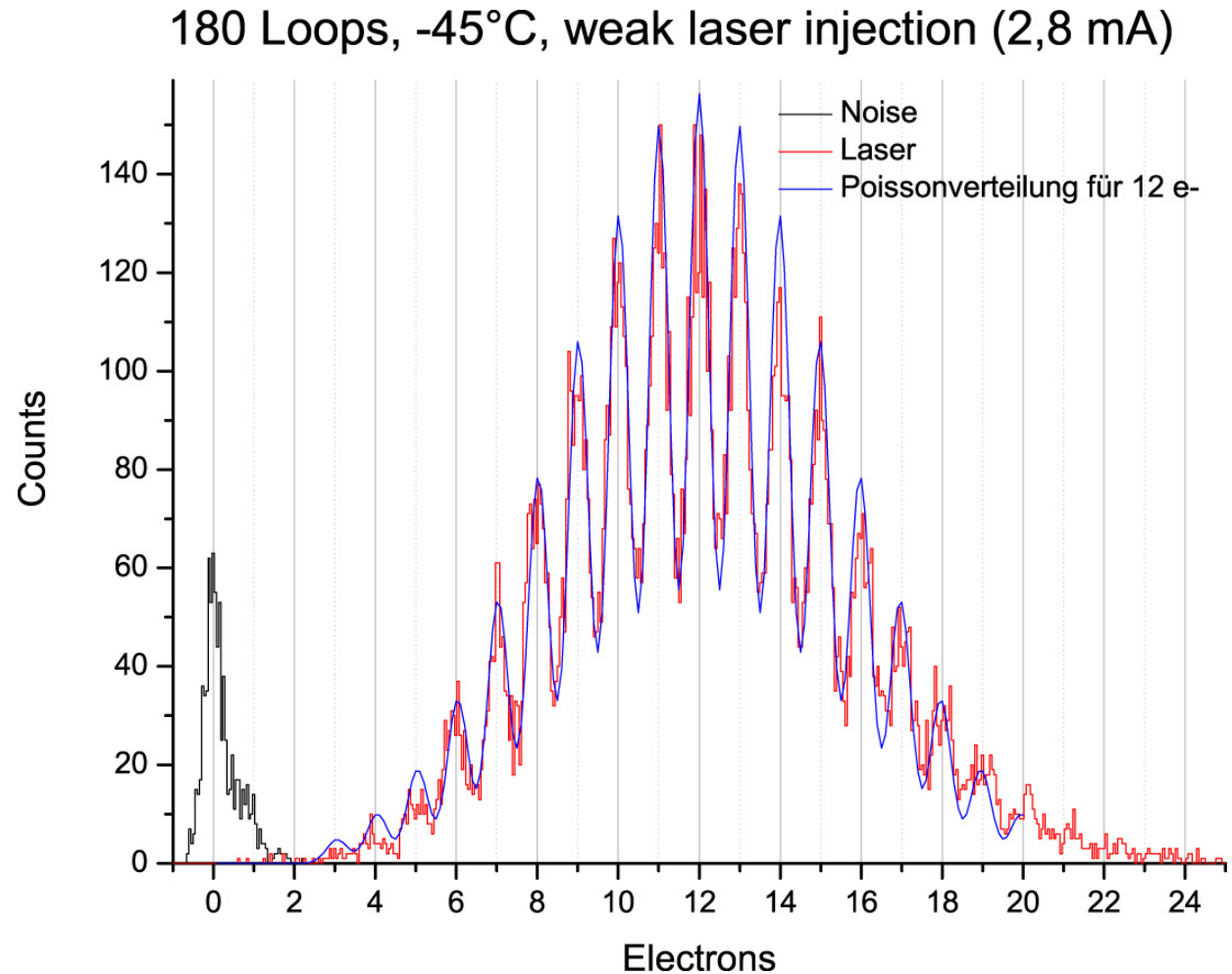
180 Loops,  $-45^{\circ}\text{C}$ , weak laser injection





# RNDR tests: low level laser light

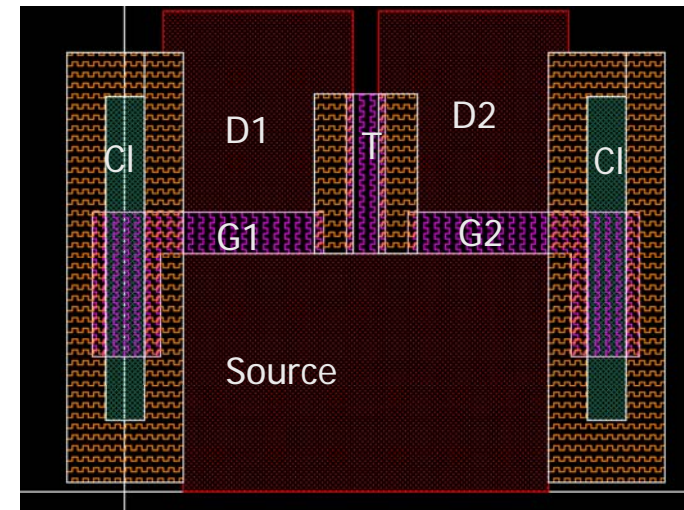
- Low number of electrons created by laser pulse
- Good separation between peaks
- Poisson distribution smeared with Gaussian fits data very well
- High energy tail of noise peak (due to leakage current) not yet taken into account properly



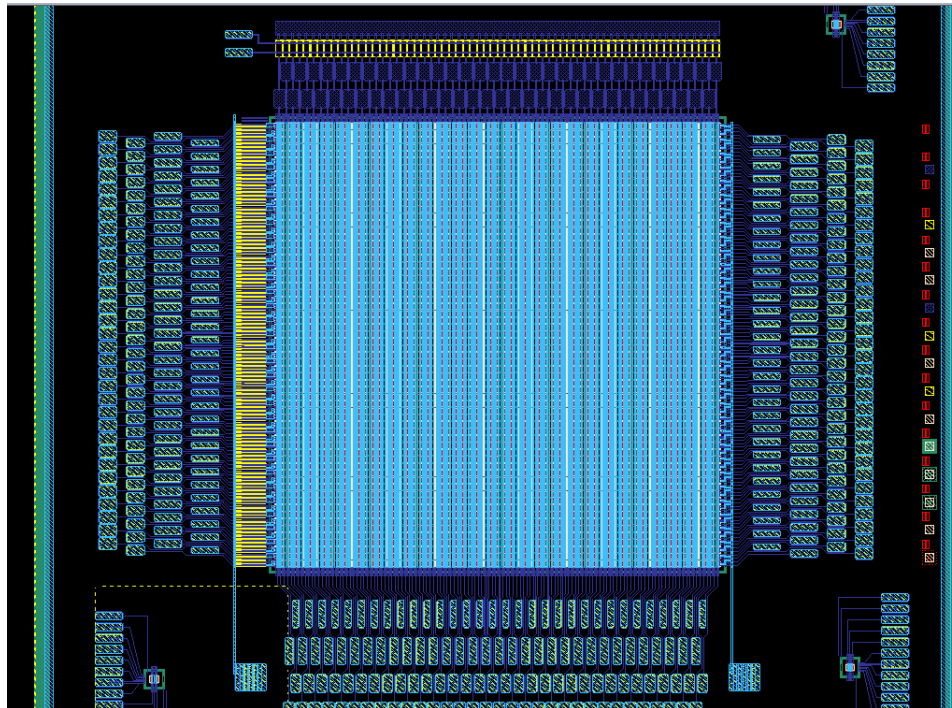


## RNDR readout: further activities

- Next generation devices:
  - Double DEPFETs with three transfer gates allowing transfer with both DEPFETs drawing current
  - Larger pixel matrices: 64x64 devices in production
- Readout with differential amplifiers
- Readout chip for matrix readout



Linear double DEPFET structure with common source and three transfer gates



Layout of 64x64 RNDR DEPFET matrix with  $75 \times 75 \mu\text{m}^2$  pixel size



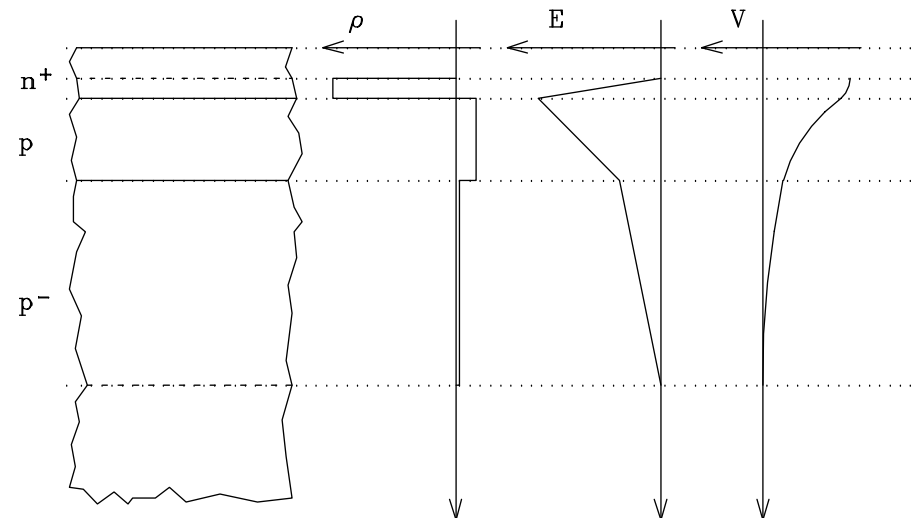
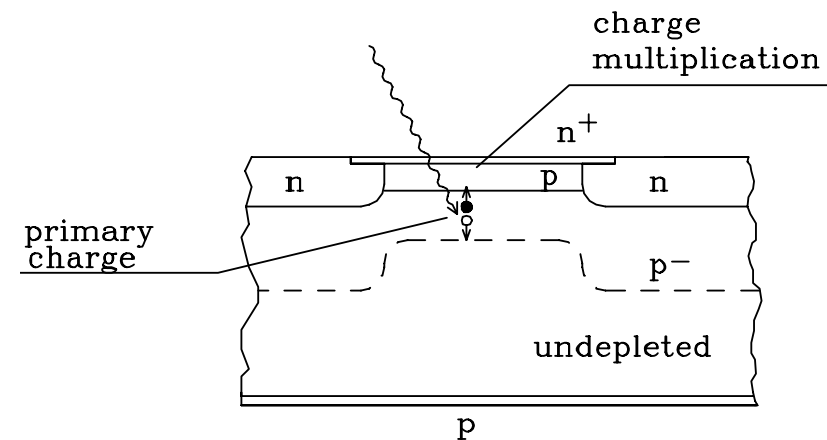
# Avalanche Detectors



# Avalanche diode

Charge multiplication in high electric field region:

- Electrons and holes are accelerated by electric field in between collisions (with lattice defects)
- Are able to create electron hole pairs if they require enough energy
- Electrons are slightly more likely to create pairs than holes
- Multiplication probability is very strongly dependent on electric field strength
- Operation regimes:
  - Proportional regime: (essentially) only electrons are multiplying
  - Breakdown regime: both carrier types multiply. Current has to be limited by external means (limited Geiger mode)
- Area device :
  - Bulk is only partially depleted
  - Non homogeneous high field region
  - Entrance window obstructed
  - Can be operated in proportional or limited Geiger mode
- Desired topology (for good efficiency):
  - long and homogeneous high field region
  - Avalanche initiated by primary electron (not hole)
  - Non obstructed radiation entrance window





# Avalanche Drift Diode





# The new avalanche amplification concept

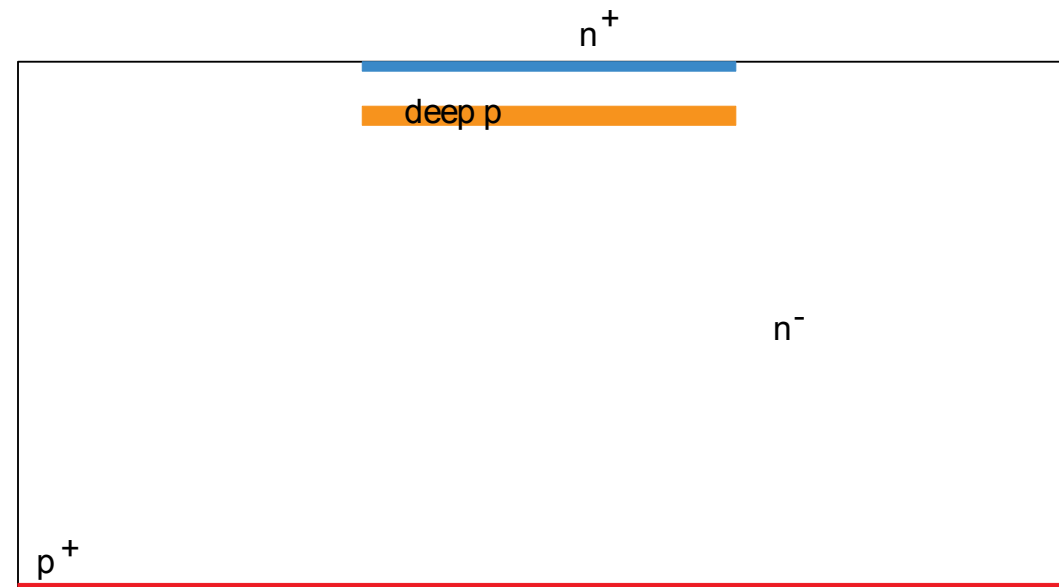
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- Basic idea:
  - Should be compatible with our fully depleted detectors:
    - PN-CCDs
    - Silicon Drift Diode
  - with radiation entrance on backside of fully depleted device
  - Focus signal electrons on (small) avalanche region
- Development of concept to be shown in several steps



# Development of concept I

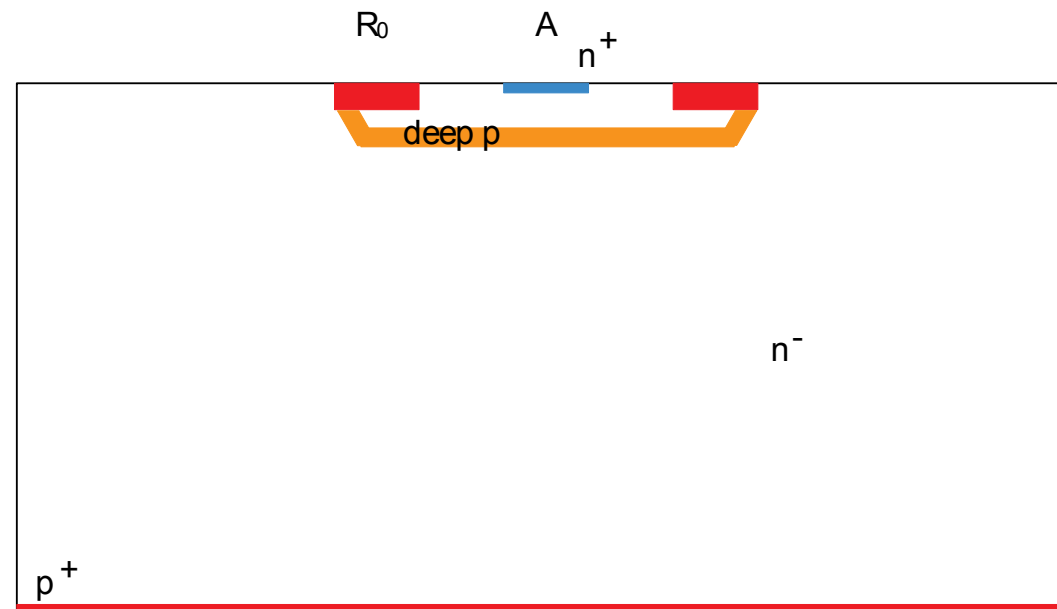
- Fully depleted bulk radiation entrance on backside
  - Adjustment of field needs large voltage variation





## Development of concept II

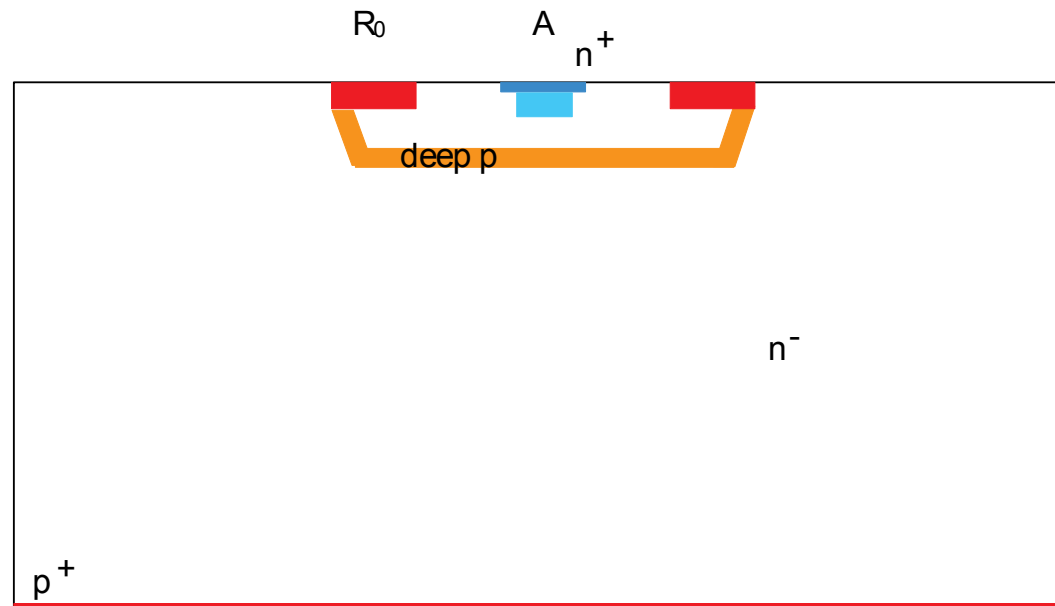
- Fully depleted bulk radiation entrance on backside
- Biasing from top ring-like structure
  - Gives better control of high field region





## Development of concept III

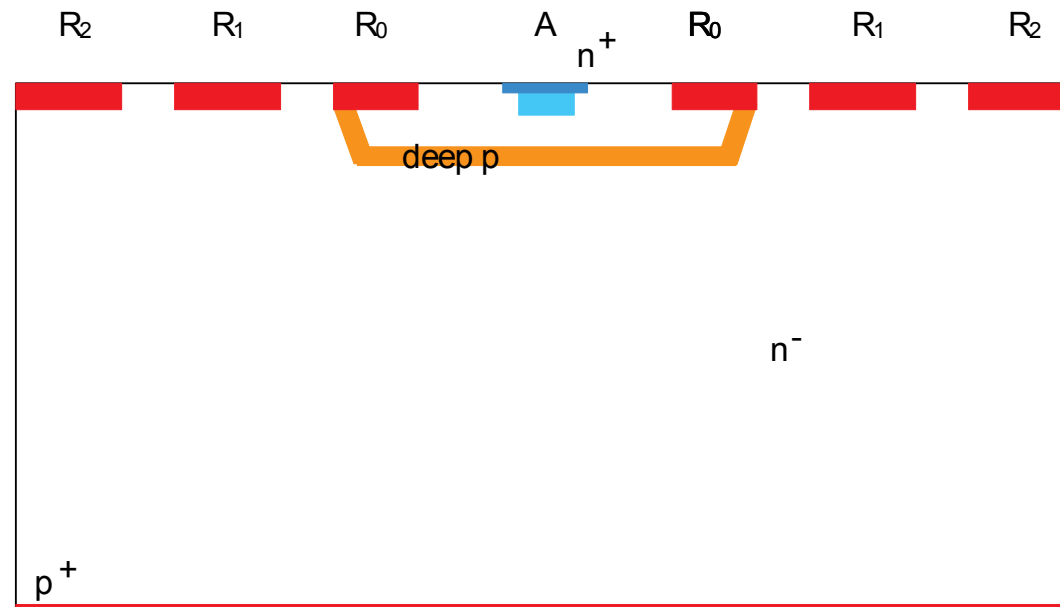
- Fully depleted bulk radiation entrance on backside
- Biasing from top ring-like structure
- Increase depth of buried p-layer ; add deep n implant to
  - Confine high field region to centre
  - Depletes buried p-layer in centre only
  - Prevents field peaks at edges





## Development of concept IV

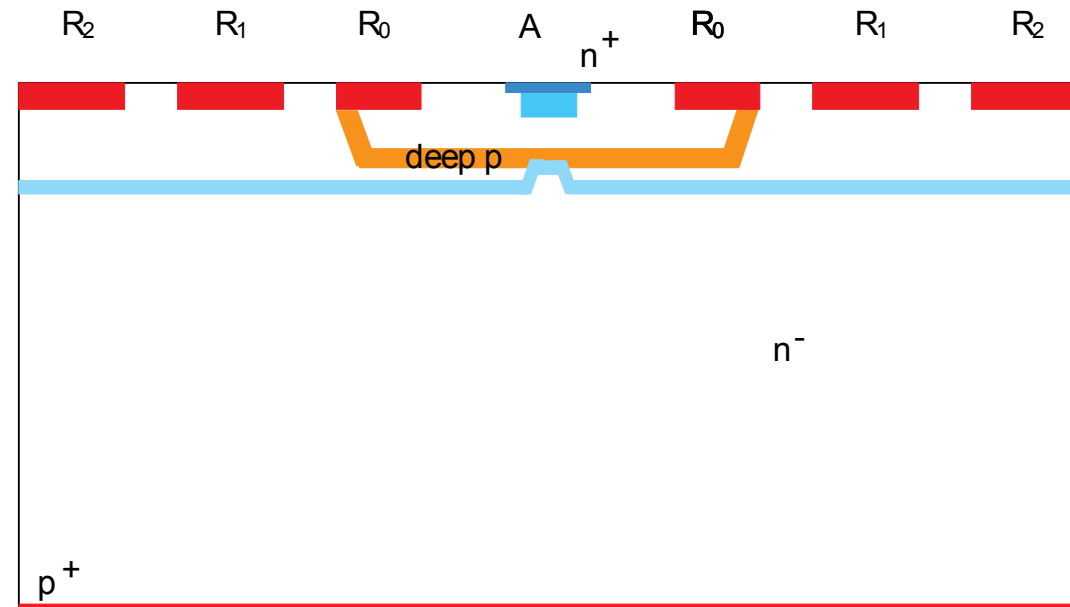
- Fully depleted bulk radiation entrance on backside
- Biasing from top ring-like structure
- Deep n implant in centre
- Addition of drift rings
  - Focusses electrons to avalanche region





## Development of concept V

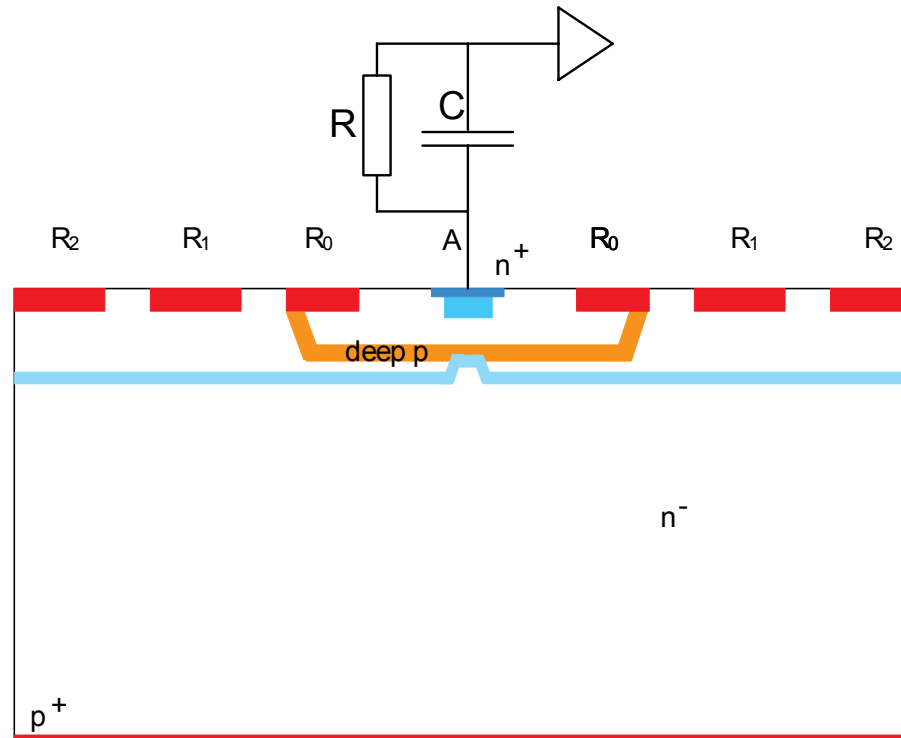
- Fully depleted bulk radiation entrance on backside
- Biasing from top ring-like structure
- Deep n implant in centre
- Addition of drift rings
- (modulated) Buried n layer
  - Prevents hole emission to backside
  - Focusses electrons to centre of avalanche region





# Limiting in Geiger mode operation

- Reduce voltage across high field region after firing

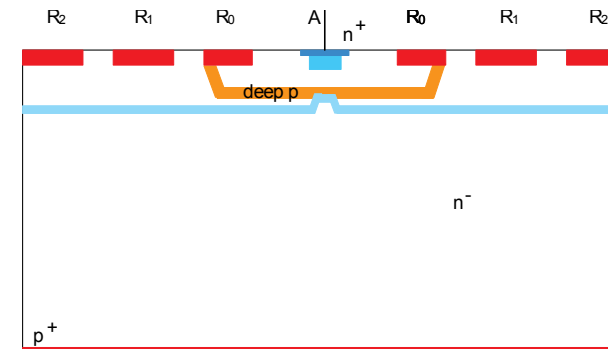


- Passive elements (resistor and capacitor) integrated into detector



# Application of new avalanche structure concept

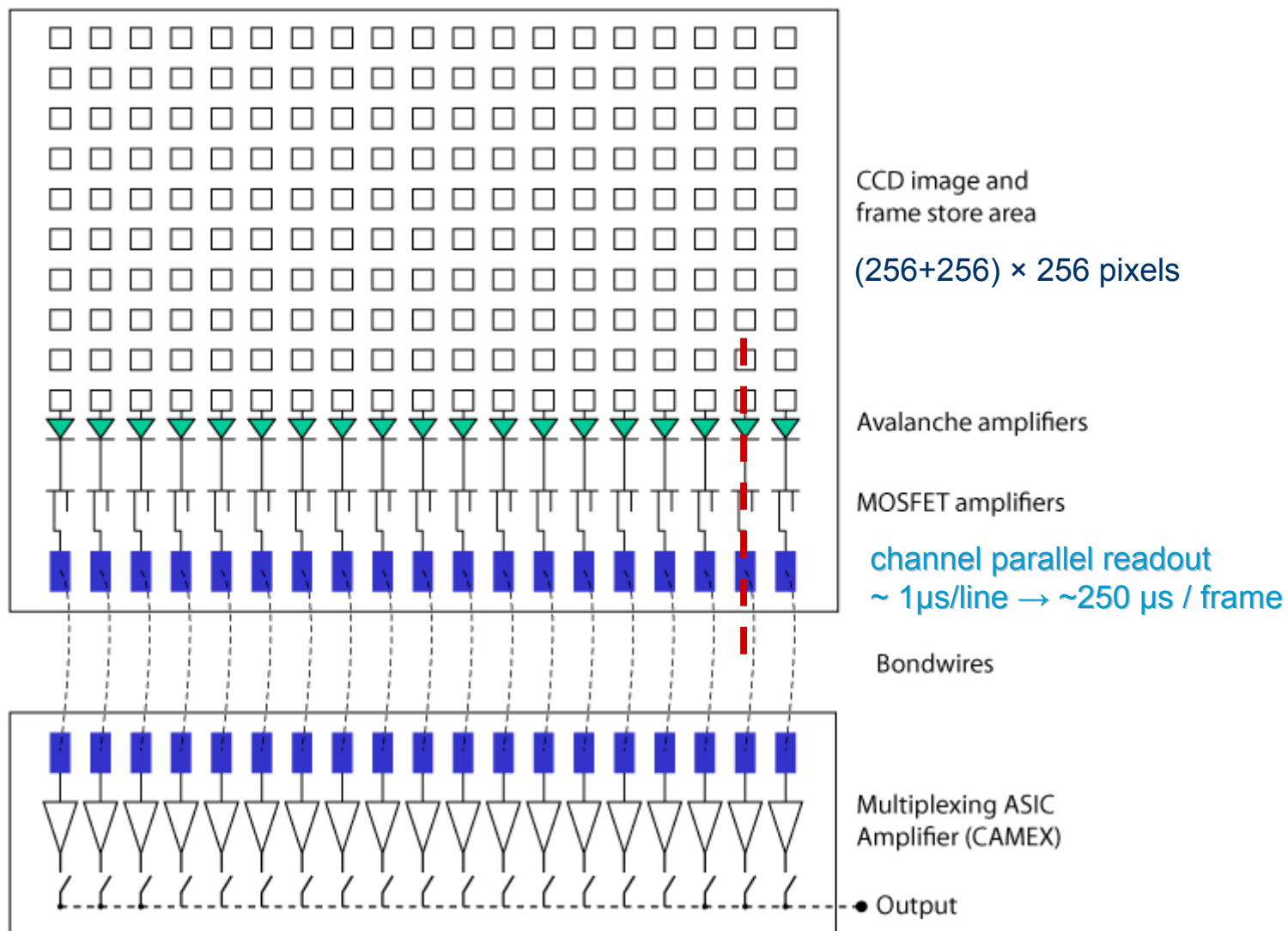
- As central element in Avalanche Drift Diode (Combination of Drift diode with avalanche amplifier)
- Avalanche Drift diode array working in limited Geiger mode as backside illuminated „Silicon Photomultiplier“
- As readout element of pnCCD for single electron detection





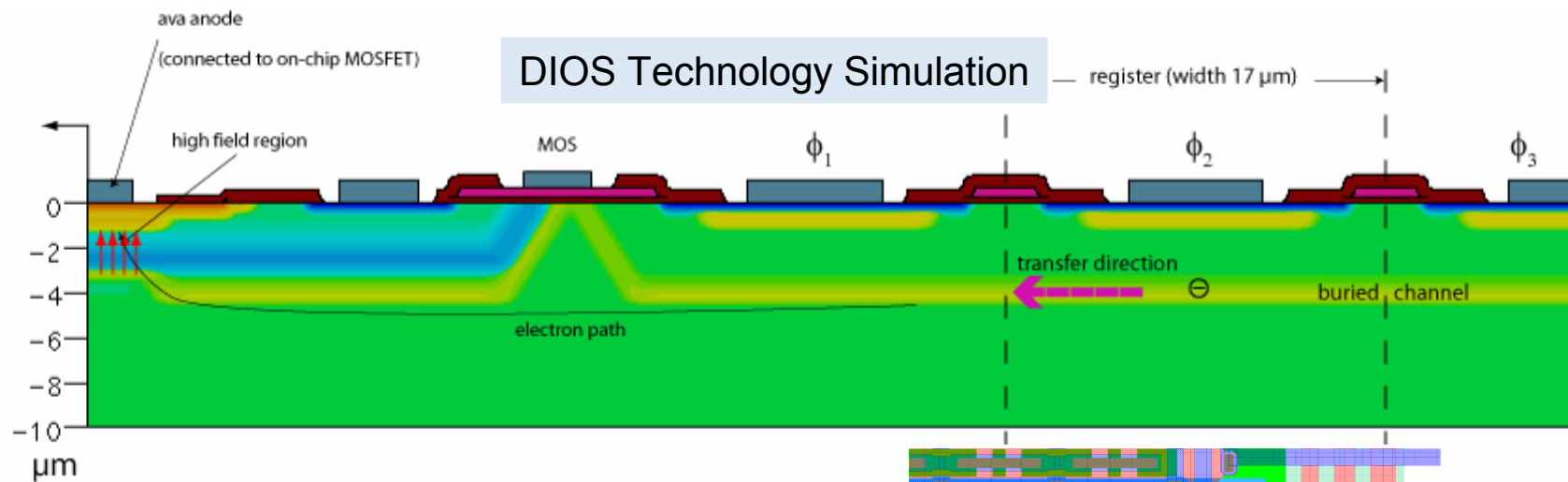


# Avalanche CCD Schematics

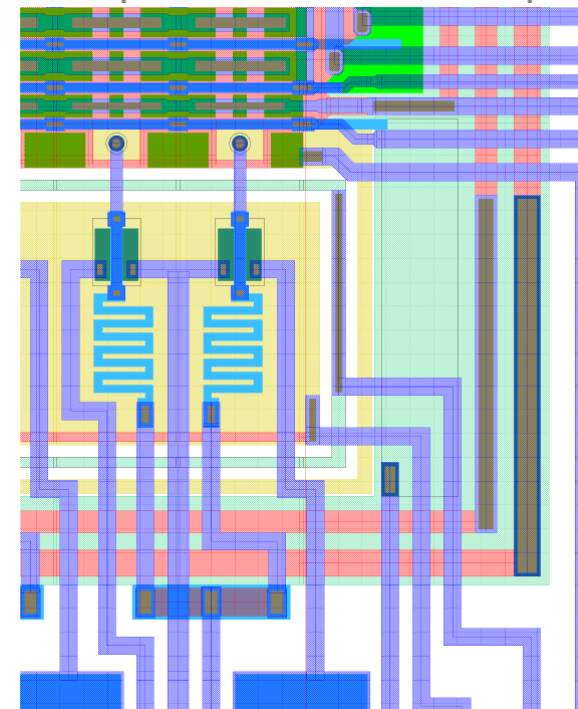




# CCD with Avalanche Diode Readout: Technology Simulation



- MOS Source follower integrated into same chip
- Production together with Backside Illuminated „Silicon Photomultipliers“



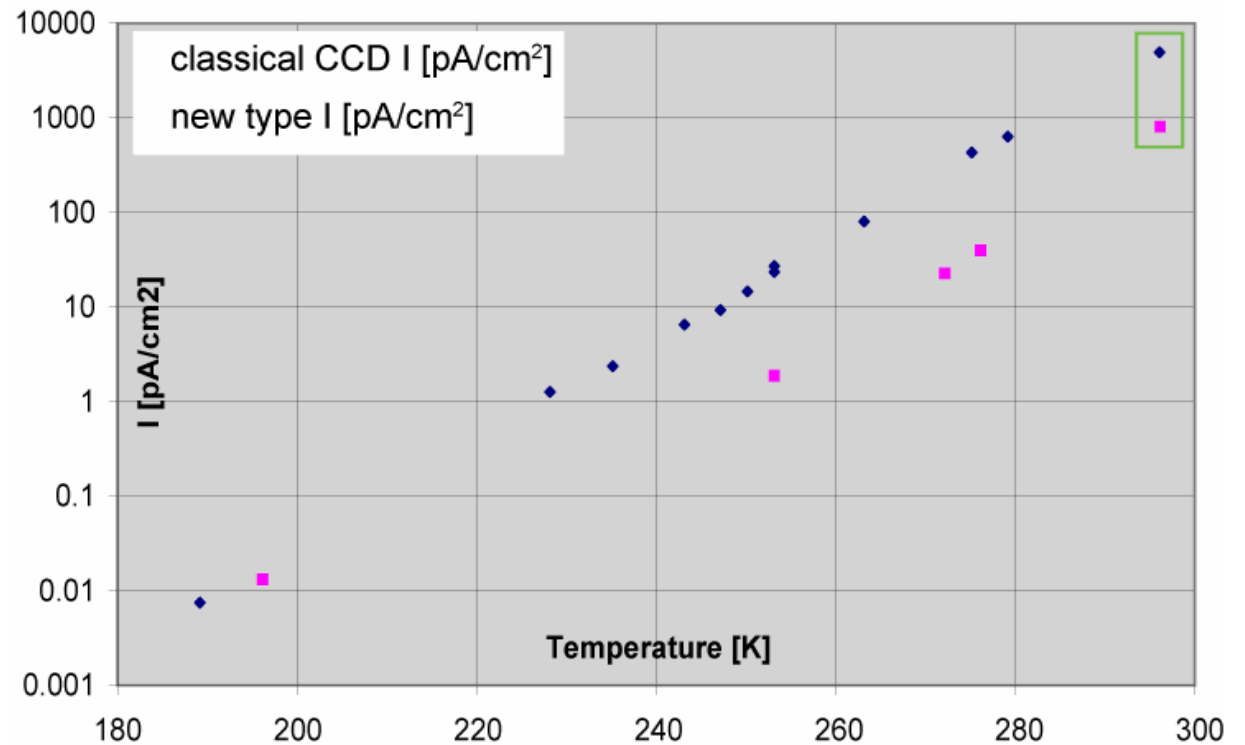


# Very Low Background Single (Optical) Photon Detectors



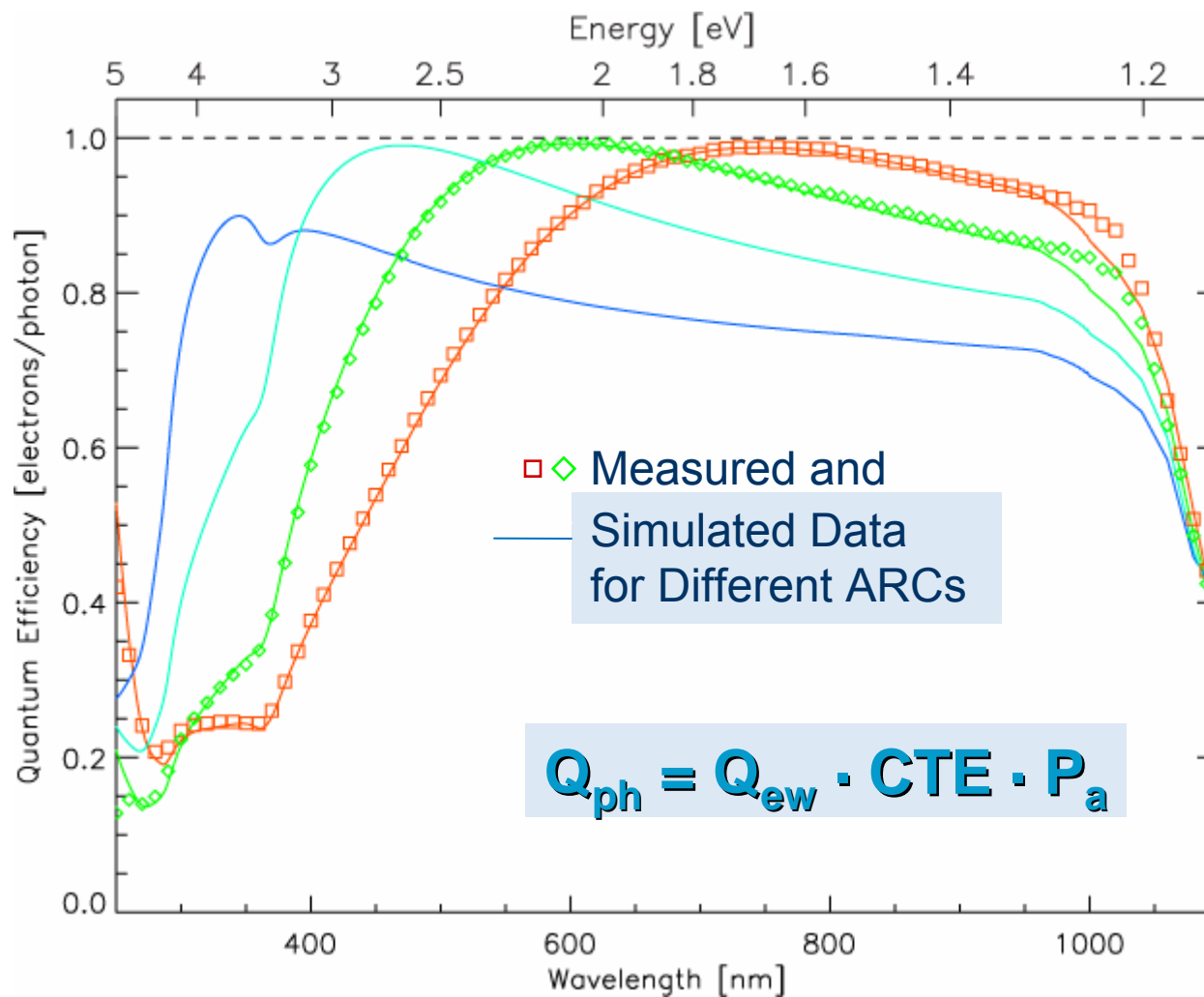
# Single electron background

- Dominant source: thermal generation of electron-hole pairs
- Can be reduced by cooling
- Measured temperature dependence of leakage current
- For 10mm<sup>2</sup> and 190K 1hour one obtains  $2 \times 10^7$  electrons
- Reduction by an order of magnitude every 20K





# Entrance Window of Back Illuminated Devices





# Background estimates

- Single electron background rates
  - Assumptions:
    - Image area size  $10\text{mm}^2$
    - Temperature  $130\text{K}$  -> scaling from measured value at  $190\text{K}$   $10^{-14}\text{ A}$  leakage current  $10^{-14} \times 10^{-3}\text{A/cm}^2 = 10^{-17}\text{A}$
    - Pixel size  $100 \times 100\ \mu\text{m}^2$  -> 10000 pixel in image area
    - Readout rate 1 frame/second
  - Dark rate in image region  
 $7\text{ el/s}$  or  $2 \times 10^4\text{ el/hour}$  in  $10\text{ mm}^2$  area
  - Dark rate in pixel  
 $7 \times 10^{-3}\text{ el/sec}$  or  $2\text{ el/hour}$
- Double electron background rate
  - Probability of collecting 2 electrons in same pixel of  $10\text{mm}^2$  area  
 $7 \times 7 \times 10^{-3} = 5 \times 10^{-2}$  double electron events/s =  $140\text{ /hour}$



## Scaling of Estimated Background Rates

Background rate scaling: events/hour in Image area

	Single electron background rates	Double electron background rates
Leakage current (I) (Temperature)	$I$	$I^2$
Image area (A)	$A$	$A$
Pixel area (P)	$1$	$P$
Charge collection time (t <sub>coll</sub> )	$1$	t <sub>coll</sub>



# Single photon sensitive detectors

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- PnCCDs with avalanche readout
  - Cannot distinguish 1 from 2 electrons
- PnCCDs with RNDR (ping-pong) readout
  - Can measure the number of electrons collected in each pixel
  - Setting threshold to two electrons would almost completely remove the background
  - This would eliminate sensitivity below approx. 3eV
- Detector development will be done for astrophysics application
- requires large effort in terms of time manpower and finances





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## Summary

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THE END